



Final Product/Process Change Notification
Document #:FPCN25729XC
Issue Date:06 Aug 2024

Title of Change:	Wafer Fab Site Transfer from LA Semiconductor Idaho, United States to onsemi Bucheon, Korea.			
Proposed First Ship date:	13 Nov 2024 or earlier if approved by customer			
Contact Information:	Contact your local onsemi Sales Office or NoorArdila.Shaharuddin@onsemi.com			
PCN Samples Contact:	<p>Contact your local onsemi Sales Office. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.</p>			
Additional Reliability Data:	Contact your local onsemi Sales Office or Nicky.Siu@onsemi.com			
Type of Notification:	<p>This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. onsemi will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact PCN.Support@onsemi.com</p>			
Marking of Parts/ Traceability of Change:	Changed material can be identified by lot code			
Change Category:	Wafer Fab Change			
Change Sub-Category(s):	Manufacturing Site Transfer			
Sites Affected:				
onsemi Sites	External Foundry/Subcon Sites			
onsemi Bucheon, Korea	None			
Description and Purpose:				
This Final Product Change Notification (FPCN) is to notify customers that the affected parts listed below will be transferred from current wafer fab LA Semiconductor Idaho, United States to onsemi Bucheon, Korea wafer fab site.				
Upon expiration of this FPCN, new manufacturing wafer fab onsemi Bucheon, Korea will be utilized to produce the affected products list.				
There are no product marking changes as a result of this change.				
Manufacturing location for Wafer Fab	From LA Semiconductor, Idaho, United States	To onsemi Bucheon, Korea		



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Reliability Data Summary:

QV DEVICE NAME: ESD9M5.0ST5G

RMS: 97093

PACKAGE: SOD923

Test	Specification	Condition	Interval	Results
High Temperature Reverse Bias	JESD22-A108	Ta=150°C, 100% max rated V	1008 hrs	0/231
High Temperature Storage Life	JESD22-A103	Ta=150°C	1008 hrs	0/231
Preconditioning	J-STD-020 JESD-A113	MSL 1 @260°C		
Temperature Cycling	JESD22-A104	Ta= -55°C to +150°C	1000 cyc	0/231
Highly Accelerated Stress Test	JESD22-A110	130°C, 85% RH, 18.8psig, bias	96 hrs	0/231
Unbiased Highly Accelerated Stress Test	JESD22-A118	130°C, 85% RH, 18.8psig, unbiased	96 hrs	0/231

Electrical Characteristics Summary:

Electrical characteristics are not impacted.

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the [PCN Customized Portal](#).

Part Number	Qualification Vehicle
ESD9R3.3ST5G	ESD9M5.0ST5G
ESD9P5.0ST5G	ESD9M5.0ST5G
ESD9M5.0ST5G	ESD9M5.0ST5G
ESD9L5.0ST5G	ESD9M5.0ST5G
ESD9L3.3ST5G	ESD9M5.0ST5G